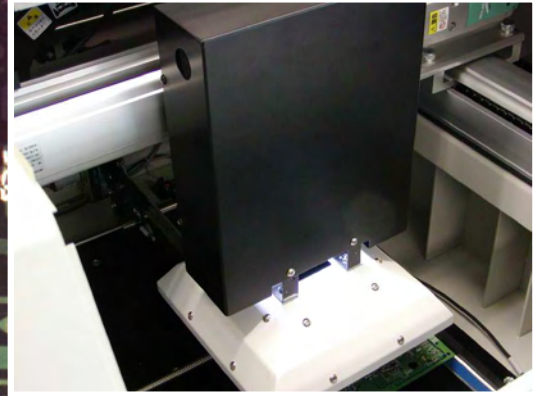
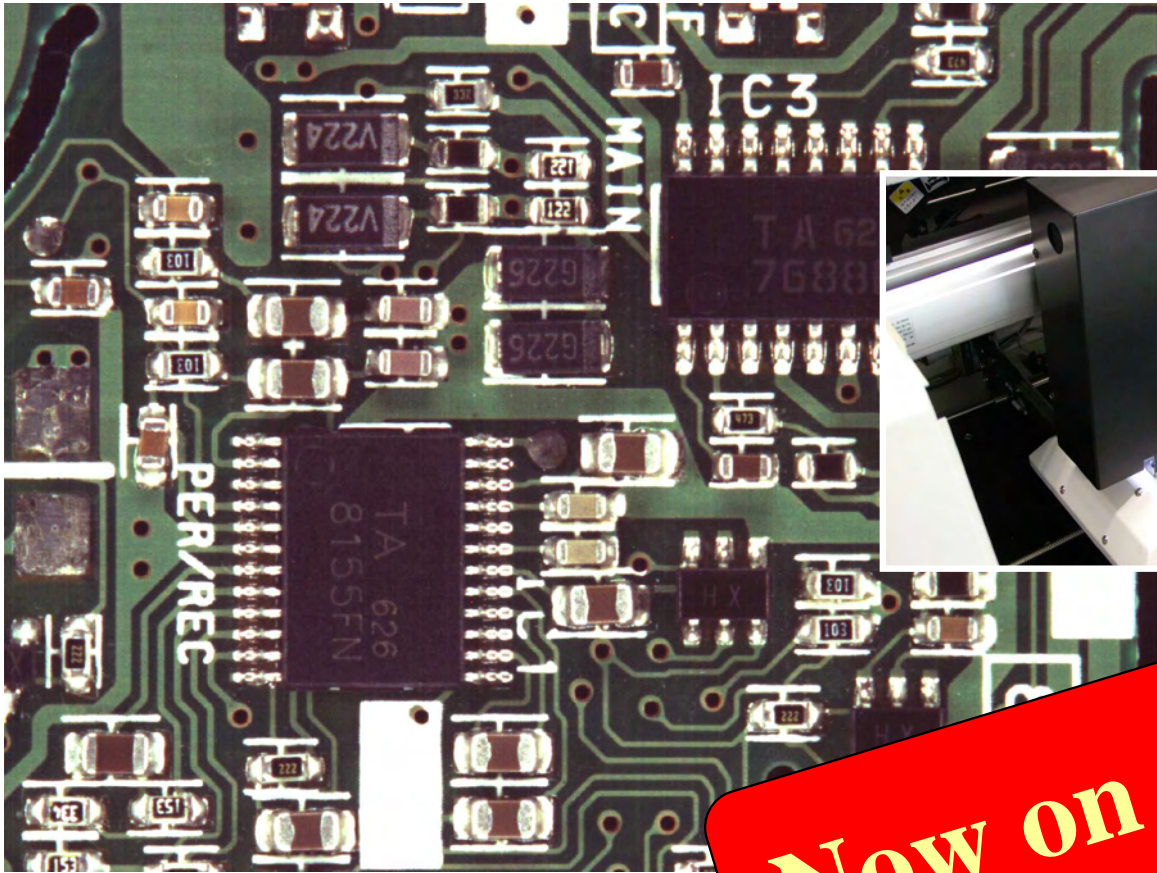




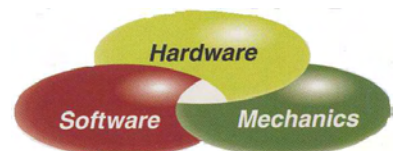
VISION TESTER

ESV-505



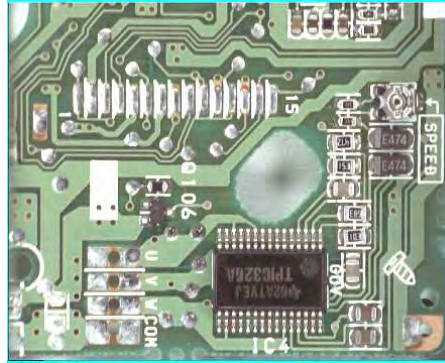
Now on Sale

High Speed Vision Inspection system by High Resolution Camera



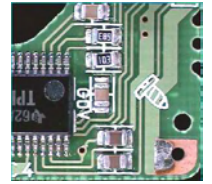
Features

- 1 **3M pixel color camera**
By high resolution camera (17 micron / pixel) be got high speed & good performance.

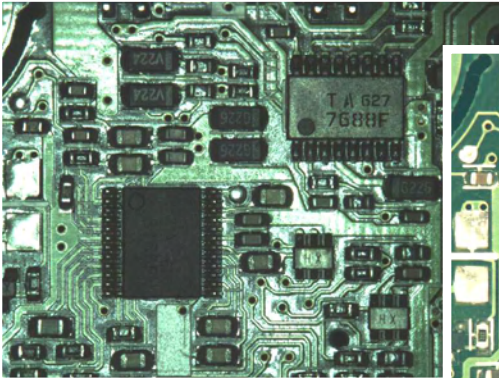


Camera view of ESV-505
35mm × 26mm

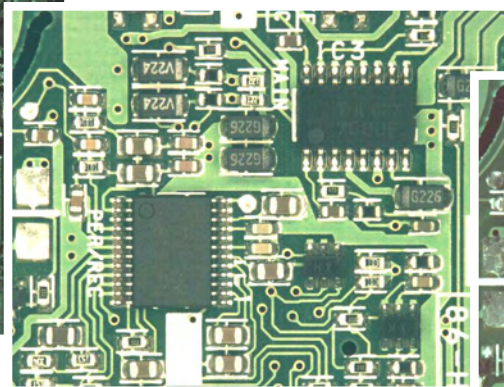
Current model
16mm × 15mm



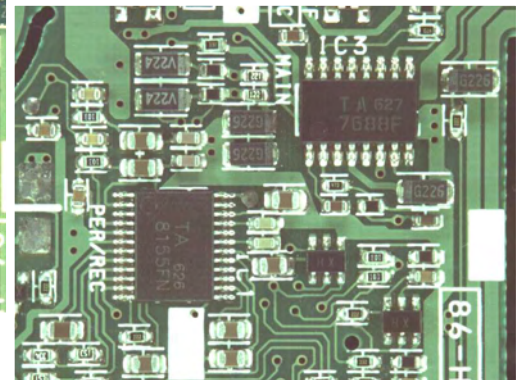
- 2 **3 type of illumination unit**
1) Coaxial top light for inspection for solder
2) Middle light for inspection for parts
3) Side light for inspection for parts



Coaxial top light



Middle light



Side light

- 3 **Improve the distortion of lens**
505 has the specially developed lens unit. This lens unit has improved the distortion of lens.

PATPEND



- 4 **Conveyer unit**
ESV-505 has conveyer unit as standard, so it is easy to set up the target PCB.



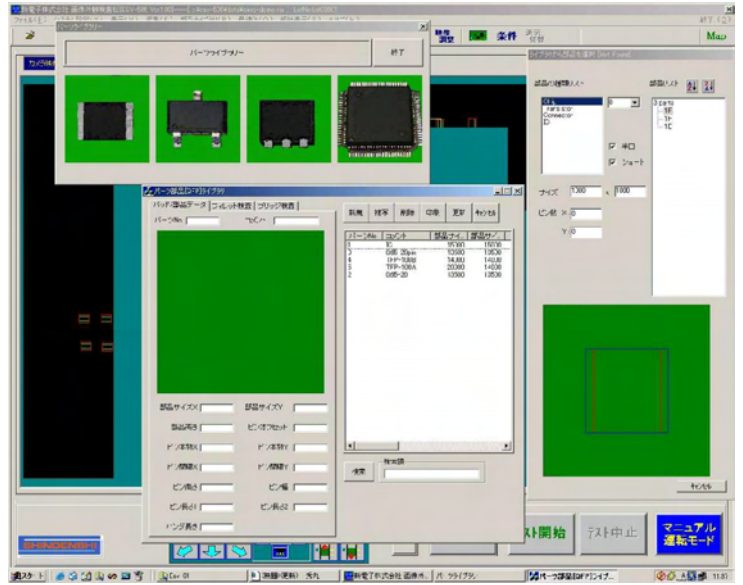
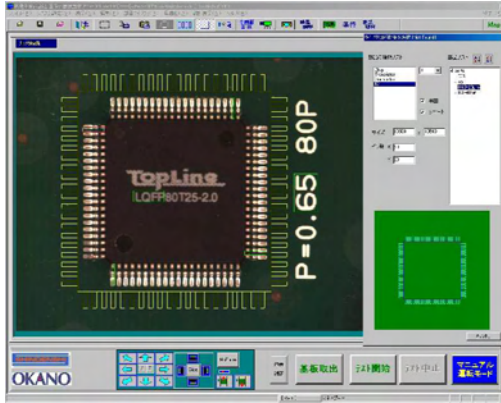
5 **Inspection method**

- 1) High speed pattern matching with normalization correlation process For component check
- 2) Pixel counting at solder area by 2D For Solder check
- 3) Density inspection by B&W gray scale For IC lead short check
- 4) Color check Inspect difference of color depend on the color balance (R, G, B) on the target.

6

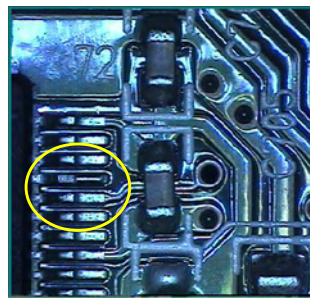
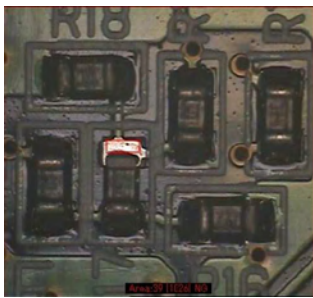
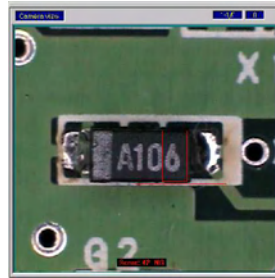
User friendly operation

After put golden board on the machine, and move camera on the target component, then resist the target image. This operation is very easy, Familiar operation! And also available parts library. So when use part library function and other existing data, can make test program at short time.



Target Defects

Missing Component	Wrong part	Part shift	Tombstone & Billboard	Solder short	Color check
Printed mark & Character	Chip component Solder file	Chip component Solder loose	Manual insertion Component Solder area	IC lead Solder area	Lead open



Option

Available to confirm the fail data on remote PC through net work LAN.

Repair station

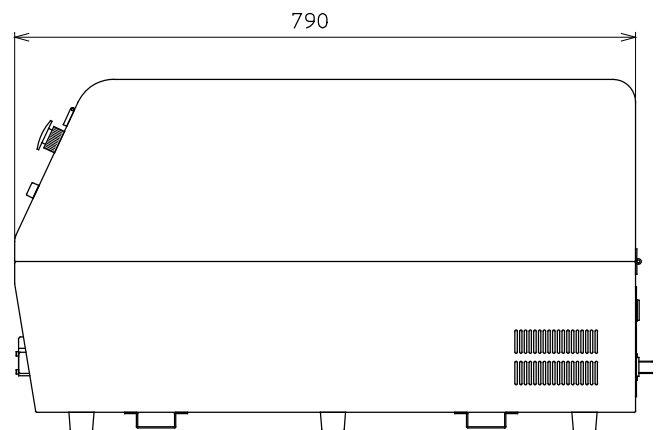
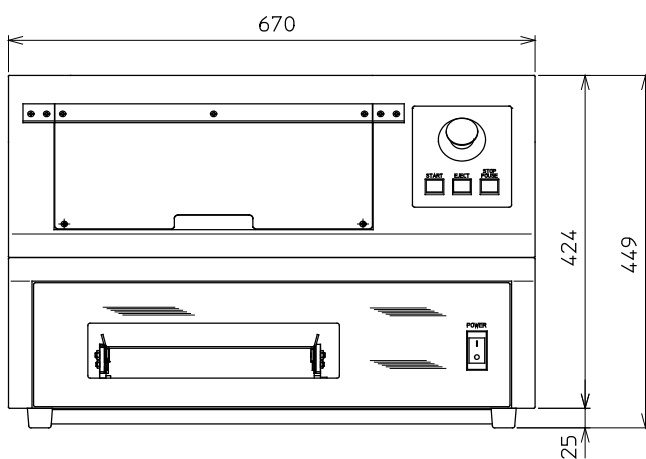


Specification for ESV-505

Dimension	670 (W) × 790 (D) × 449 (H) mm
Weight	Apporox 70kg
In put	AC 100 V or AC 200V (Note: 1)
Power consumption	300 W (exclude PC & Monitor)
Max. driving speed	500 mm / sec
Repetability	± 25 micron or less
Max. processing speed	16 ms / part (128 × 128 pixel)
Max. target size	290× 370 mm
Camera	3M pixel Color camera (2048 x 1536 pixel)
Light source	Coaxial top, Side, Middle
Resolution	17 micron / pixel
Frame size	35 mm × 26 mm
Inspection method	Pattern matching, RGB color check, Area, Gray scale
PC	Windows XP / 2000

Note 1 : Available to select in put voltage when making an order.

Overall dimension



Above specifications may change without prior notice.

SHINDENSHI

Shindenshi Corp.,

Nozaki 3-22-20, Mitaka, Tokyo, Japan

TEL: +81 422 31 5530 FAX: +81 422 31 2988

Internet Home Page <http://www.shindenshi.co.jp>

2005/04